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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar et al.

Title: APPARATUS AND METHOD FOR PRINTING MICRO METAL STRUCTURES

Docket No.: 1303.096US1

Serial No.: 10/602322

Filed: June 24, 2003

Due Date: N/A

Examiner: Unknown

Group Art Unit: 1763

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450


We are transmitting herewith the following attached items (as indicated with an "X"):

X A return postcard.


X An Information Disclosure Statement (2 pgs.), Form 1449 (2 pgs.), and copies of 17 cited documents.

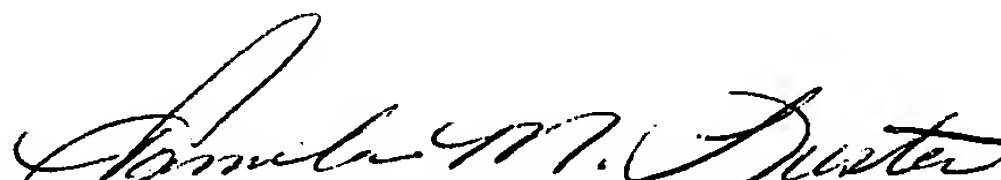
Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: 
Atty: David C. Peterson
Reg. No. 47,857

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 3rd day of September, 2004.


Name


Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)

S/N 10/602322



PATENT

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INFORMATION DISCLOSURE STATEMENT

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. § 1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

Serial No :10/602322

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Title: APPARATUS AND METHOD FOR PRINTING MICRO METAL STRUCTURES

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Dkt: 1303.096US1

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

PAUL A. FARRAR ET AL.

By their Representatives,

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9-3-04

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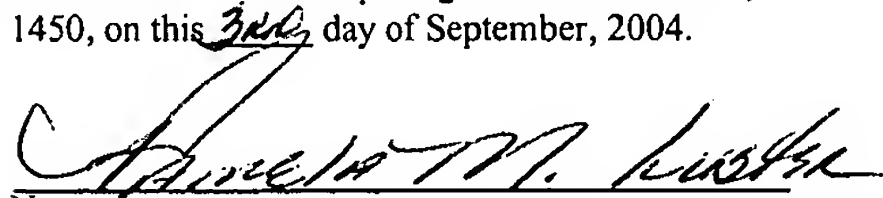


David C. Peterson

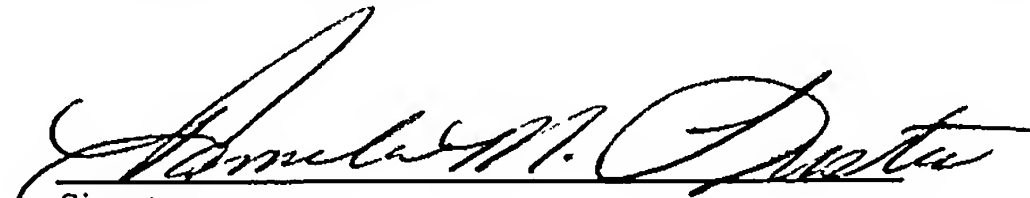
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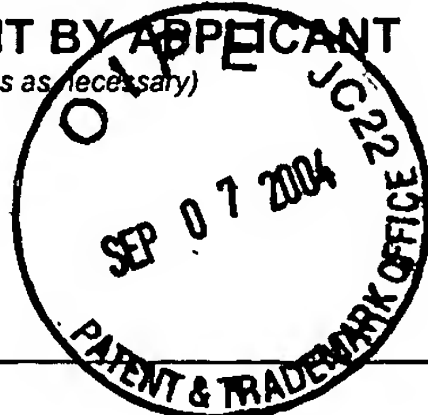


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Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number	10/602322
Filing Date	June 24, 2003
First Named Inventor	Farrar, Paul
Group Art Unit	1763
Examiner Name	Unknown

Sheet 1 of 1

Attorney Docket No: 1303.096US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US2001/0014524	08/16/2001	Farrar, Paul A.	438	613	02/19/1999
	US2002/0034581	03/21/2002	Farrar, Paul A., et al.	427	58	02/20/2001
	US-3,959,047	05/25/1976	Alberts, G. S., et al.	156	8	09/30/1974
	US-5,457,345	10/10/1995	Cook, H. C., et al.	257	766	01/14/1994
	US-5,461,257	10/24/1995	Hundt, M. J.	257	707	03/31/1994
	US-5,642,261	06/24/1997	Bond, R. H., et al.	361	704	06/30/1994
	US-5,693,572	12/02/1997	Bond, R. H., et al.	437	209	01/18/1996
	US-6,136,689	10/24/2000	Farrar, Paul A.	438	626	08/14/1998
	US-6,435,396	08/20/2002	Eldridge, Jerome M.	228	33	04/10/2000

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		ANONYMOUS, "Combination Process for Final Metal Lines and Metal Terminals", Kenneth Mason Publications Ltd, Research Disclosure No. 342, England,(Oct. 1992),1 page	
		ANONYMOUS, "Process for High Density of Chip Terminals on Large Wafers", Kenneth Mason Publications Ltd, Research Disclosure No. 02, England,(Feb. 1993),1 page	
		BABIARZ, A J., "Key Process Controls for Underfilling Flip Chips", <u>Solid State Technology</u> , 40(4), (April 1997),77-8, 81, 83	
		JONES, P , et al., "Bumped Wafers, Worth Their Weight in Gold?", <u>Advanced Packaging</u> , 8(1), (January 1997),54-57	
		MARCOTTE, V. C., "Review of Flip Chip Bonding", <u>Proceedings of the 2nd ASM International Electronic Materials and Processing Congress</u> , 24-28 April 1989, Philadelphia, PA, (1989),73-81	
		MINGES, MERRILL , "Electronic Materials Handbook", <u>Materials Park, OH : ASM International</u> , (1989),301, 440	
		PUTTLITZ, KARL J., et al., "Solder Transfer Technique for Flip-Chip and Electronic Assembly Applications", <u>IEEE Transactions on Components, Packaging and Manufacturing Technology</u> , Part C, Volume 21, No. 3, (July 1998),182-188	
		RYAN, J. G., "Technology Challenges for Advanced Interconnects", <u>Advances in Metallization and Interconnect Systems for ULSI Applications</u> , September 30 - October 2, 1997, San Diego CA, (1997),1-5	

EXAMINER**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached